

ELECTROLESS PURE PALLADIUM PLATING SOLUTION

ABSTRACT

An electroless pure palladium plating solution capable of forming pure palladium plating films having less plating film variations is provided. The electroless pure palladium plating solution comprises an aqueous solution containing (a) 0.001 to 0.5 mol/liter of a water-soluble palladium compound, (b) 0.005 to 10 mol/liter of at least two members selected from the group consisting of aliphatic carboxylic acids and water-soluble salts thereof, (c) 0.005 to 10 mol/liter of phosphoric acid and/or a phosphate, and (d) 0.005 to 10 mol/liter of sulfuric acid and/or a sulfate.